

# ±40V, ±16A, 18.5mΩ&37.3mΩ N And P-channel Power Trench MOSFET

## JMTG170C04D

### Features

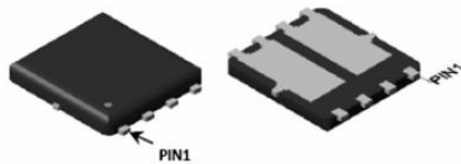
- Excellent  $R_{DS(ON)}$  and Low Gate Charge
- 100% UIS TESTED
- 100%  $\Delta V_{ds}$  TESTED
- Halogen-free; RoHS-compliant
- Pb-free plating

### Applications

- Load Switch
- PWM Application
- Power Management

### Product Summary

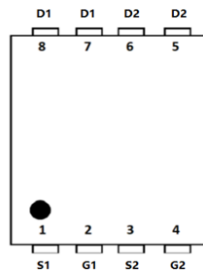
Parameters	N	P	Unit
$V_{DSS}$	40	-40	V
$V_{GS(th\_Typ)}$	1.9	-1.6	V
$I_D(@V_{GS}=10V)$	16	-16	A
$R_{DS(ON\_Typ)}(@V_{GS}=10V)$	14.4	31.1	mΩ
$R_{DS(ON\_Typ)}(@V_{GS}=4.5V)$	18.5	37.3	mΩ



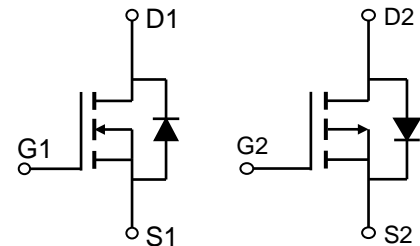
Top View

Bottom View

PDFN5x6-8L-D



Pin Assignment



Schematic Diagram

### Ordering Information

Device	Marking	MSL	Form	Package	Reel(pcs)	Per Carton (pcs)
JMTG170C04D	G170C04D	1	Tape&Reel	PDFN5x6-8L-D	5000	50000

### Absolute Maximum Ratings (@ $T_C = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Value-N	Value-P	Unit
$V_{DS}$	Drain-to-Source Voltage	40	-40	V
$V_{GS}$	Gate-to-Source Voltage	±20		V
$I_D$	Continuous Drain Current	$T_C = 25^\circ\text{C}$	16	-16
		$T_C = 100^\circ\text{C}$	11	-11
$I_{DM}$	Pulsed Drain Current <sup>(1)</sup>	Refer to Fig.4		A
$E_{AS}$	Single Pulsed Avalanche Energy <sup>(2)</sup>	24	24	mJ
$P_D$	Power Dissipation	$T_C = 25^\circ\text{C}$	43	54
		$T_C = 100^\circ\text{C}$	17.2	21.5
$T_J, T_{STG}$	Junction & Storage Temperature Range	-55 to 150		°C

### Thermal Characteristics

Symbol	Parameter	Max	Unit
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient <sup>(3)</sup>	57	59
$R_{\theta JC}$	Thermal Resistance, Junction to Case	2.9	2.3

**Electrical Characteristics-N**( $T_J = 25^\circ\text{C}$  unless otherwise specified)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
<b>Off Characteristics</b>						
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$I_D = 250\mu\text{A}$ , $V_{GS} = 0\text{V}$	40	-	-	V
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS} = 40\text{V}$ , $V_{GS} = 0\text{V}$	-	-	1.0	$\mu\text{A}$
$I_{GSS}$	Gate-Body Leakage Current	$V_{DS} = 0\text{V}$ , $V_{GS} = \pm 20\text{V}$	-	-	$\pm 100$	nA
<b>On Characteristics</b>						
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}$ , $I_D = 250\mu\text{A}$	1.3	1.9	2.5	V
$R_{DS(ON)}$	Static Drain-Source ON-Resistance <sup>(4)</sup>	$V_{GS} = 10\text{V}$ , $I_D = 15\text{A}$	-	14.4	20	$\text{m}\Omega$
		$V_{GS} = 4.5\text{V}$ , $I_D = 10\text{A}$	-	18.5	29	$\text{m}\Omega$
<b>Dynamic Characteristics</b>						
$R_g$	Gate Resistance	$f = 1\text{MHz}$	-	2.6	-	$\Omega$
$C_{iss}$	Input Capacitance	$V_{GS} = 0\text{V}$ , $V_{DS} = 20\text{V}$ , $f = 1\text{MHz}$	-	1114	-	pF
$C_{oss}$	Output Capacitance		-	75	-	pF
$C_{rss}$	Reverse Transfer Capacitance		-	61	-	pF
$Q_g$	Total Gate Charge	$V_{GS} = 0$ to $10\text{V}$ $V_{DS} = 20\text{V}$ , $I_D = 5\text{A}$	-	22	-	nC
$Q_{gs}$	Gate Source Charge		-	4.2	-	nC
$Q_{gd}$	Gate Drain("Miller") Charge		-	3.9	-	nC
<b>Switching Characteristics</b>						
$t_{d(on)}$	Turn-On DelayTime	$V_{GS} = 10\text{V}$ , $V_{DD} = 20\text{V}$ $I_D = 5\text{A}$ , $R_{GEN} = 2.7\Omega$	-	6	-	ns
$t_r$	Turn-On Rise Time		-	6	-	ns
$t_{d(off)}$	Turn-Off DelayTime		-	24	-	ns
$t_f$	Turn-Off Fall Time		-	3	-	ns
<b>Body Diode Characteristics</b>						
$I_S$	Maximum Continuous Body Diode Forward Current		-	-	16	A
$I_{SM}$	Maximum Pulsed Body Diode Forward Current		-	-	65	A
$V_{SD}$	Body Diode Forward Voltage	$V_{GS} = 0\text{V}$ , $I_S = 15\text{A}$	-		1.2	V
$t_{rr}$	Body Diode Reverse Recovery Time	$I_F = 5\text{A}$ , $di/dt = 100\text{A}/\mu\text{s}$	-	10	-	ns
$Q_{rr}$	Body Diode Reverse Recovery Charge		-	4.8	-	nC

- Notes:
1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.
  2.  $E_{AS}$  condition: Starting  $T_J = 25^\circ\text{C}$ ,  $V_{DD} = 20\text{V}$ ,  $V_G = 10\text{V}$ ,  $R_G = 25\text{ohm}$ ,  $L = 0.5\text{mH}$ ,  $I_{AS} = 9.8\text{A}$ ,  $V_{DD} = 0\text{V}$  during time in avalanche.
  3.  $R_{\theta JA}$  is measured with the device mounted on a  $1\text{inch}^2$  pad of 2oz copper FR4 PCB.
  4. Pulse Test: Pulse Width  $\leq 300\mu\text{s}$ , Duty Cycle  $\leq 0.5\%$ .



**Electrical Characteristics-P** ( $T_J = 25^\circ\text{C}$  unless otherwise specified)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
<b>Off Characteristics</b>						
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$I_D = -250\mu\text{A}, V_{GS} = 0\text{V}$	-40	-	-	V
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS} = -40\text{V}, V_{GS} = 0\text{V}$	-	-	-1.0	$\mu\text{A}$
$I_{GSS}$	Gate-Body Leakage Current	$V_{DS} = 0\text{V}, V_{GS} = \pm 20\text{V}$	-	-	$\pm 100$	nA
<b>On Characteristics</b>						
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = -250\mu\text{A}$	-1.1	-1.6	-2.5	V
$R_{DS(ON)}$	Static Drain-Source ON-Resistance <sup>(5)</sup>	$V_{GS} = -10\text{V}, I_D = -8\text{A}$	-	31	50	$\text{m}\Omega$
		$V_{GS} = -4.5\text{V}, I_D = -5\text{A}$	-	37	65	$\text{m}\Omega$
<b>Dynamic Characteristics</b>						
$R_g$	Gate Resistance	$f = 1\text{MHz}$	-	12	-	$\Omega$
$C_{iss}$	Input Capacitance	$V_{GS} = 0\text{V}, V_{DS} = -20\text{V}, f = 1\text{MHz}$	-	1157	-	pF
$C_{oss}$	Output Capacitance		-	89	-	pF
$C_{rss}$	Reverse Transfer Capacitance		-	73	-	pF
$Q_g$	Total Gate Charge	$V_{GS} = 0 \text{ to } -4.5\text{V}$ $V_{DS} = -20\text{V}, I_D = -5\text{A}$	-	22	-	nC
$Q_{gs}$	Gate Source Charge		-	4	-	nC
$Q_{gd}$	Gate Drain("Miller") Charge		-	4	-	nC
<b>Switching Characteristics</b>						
$t_{d(on)}$	Turn-On DelayTime	$V_{GS} = -10\text{V}, V_{DD} = -20\text{V}$ $I_D = -5\text{A}, R_{GEN} = 2.7\Omega$	-	5	-	ns
$t_r$	Turn-On Rise Time		-	2	-	ns
$t_{d(off)}$	Turn-Off DelayTime		-	58	-	ns
$t_f$	Turn-Off Fall Time		-	27	-	ns
<b>Body Diode Characteristics</b>						
$I_S$	Maximum Continuous Body Diode Forward Current		-	-	-4	A
$I_{SM}$	Maximum Pulsed Body Diode Forward Current		-	-	-14	A
$V_{SD}$	Body Diode Forward Voltage	$V_{GS} = 0\text{V}, I_S = -8\text{A}$	-		1.2	V
$t_{rr}$	Body Diode Reverse Recovery Time	$I_F = -5\text{A}, di/dt = 100\text{A/us}$	-	12	-	ns
$Q_{rr}$	Body Diode Reverse Recovery Charge		-	6.6	-	nC

- Notes:
1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.
  2.  $E_{AS}$  condition: Starting  $T_J=25^\circ\text{C}$ ,  $V_{DD}=-20\text{V}$ ,  $V_G=-10\text{V}$ ,  $R_G=25\text{ohm}$ ,  $L=0.5\text{mH}$ ,  $I_{AS}=-9.8\text{A}$ ,  $V_{DD}=0\text{V}$  during time in avalanche.
  3.  $R_{\theta JA}$  is measured with the device mounted on a minimum recommended pad of 2oz copper FR4 PCB.
  4.  $R_{\theta JA}$  is measured with the device mounted on a 1inch<sup>2</sup> pad of 2oz copper FR4 PCB.
  5. Pulse Test: Pulse Width  $\leq 300\mu\text{s}$ , Duty Cycle  $\leq 0.5\%$ .



## Typical Performance Characteristics-N

Figure 1: Power De-rating

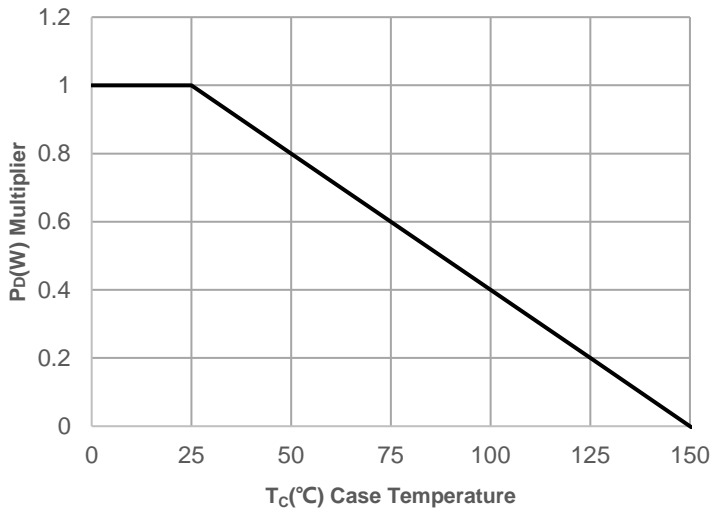


Figure 2: Current De-rating

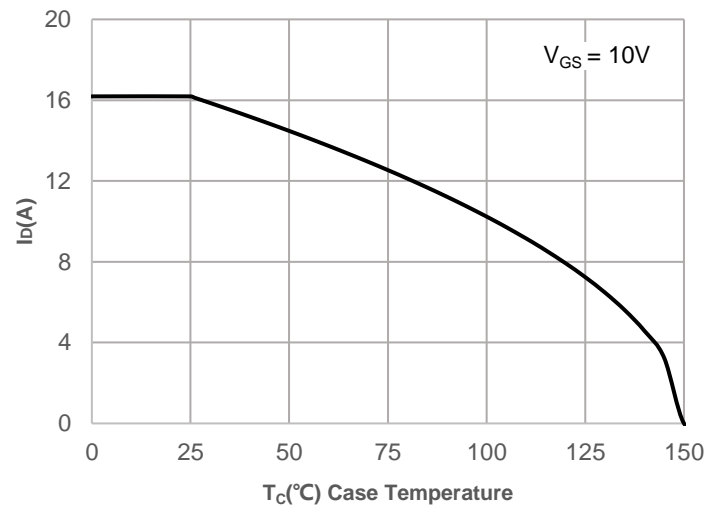


Figure 3: Normalized Maximum Transient Thermal Impedance

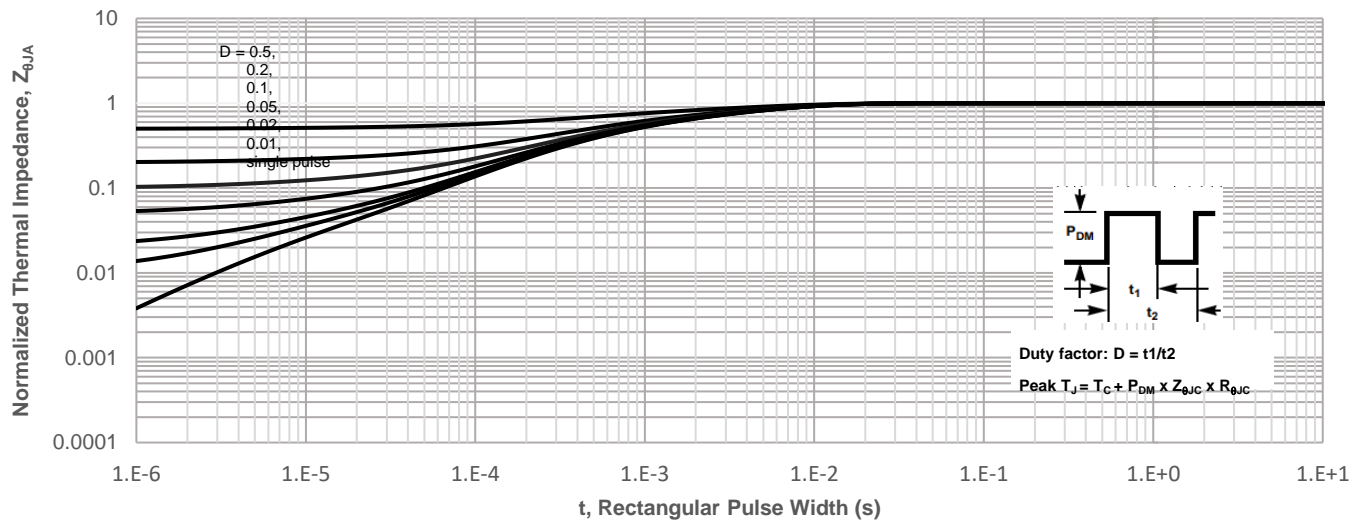
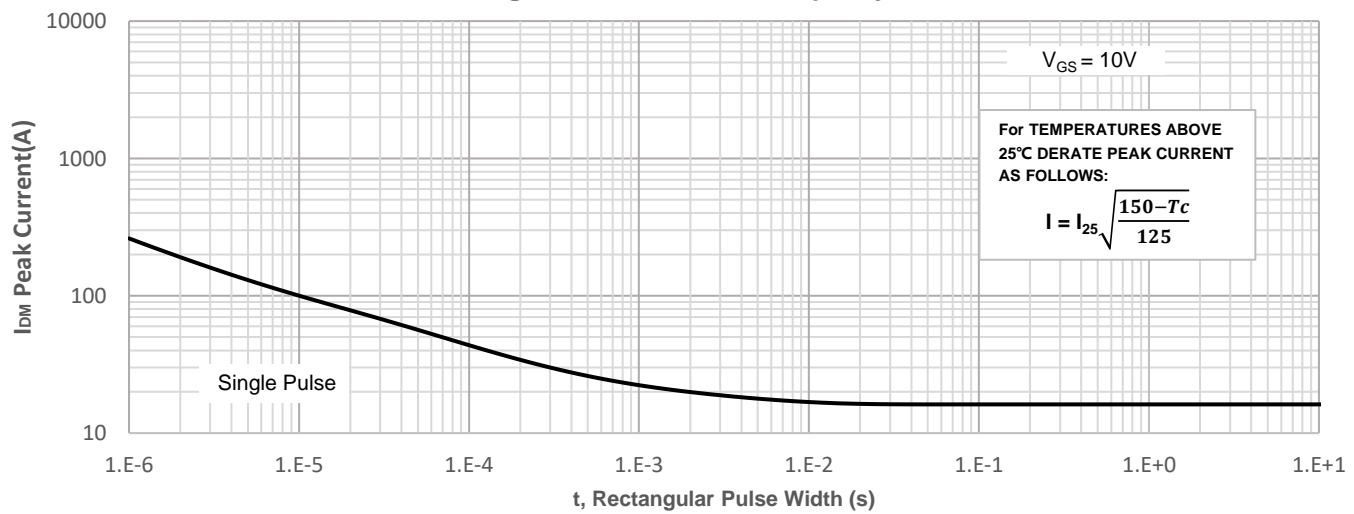


Figure 4: Peak Current Capacity



## Typical Performance Characteristics-N

Figure 5: Output Characteristics

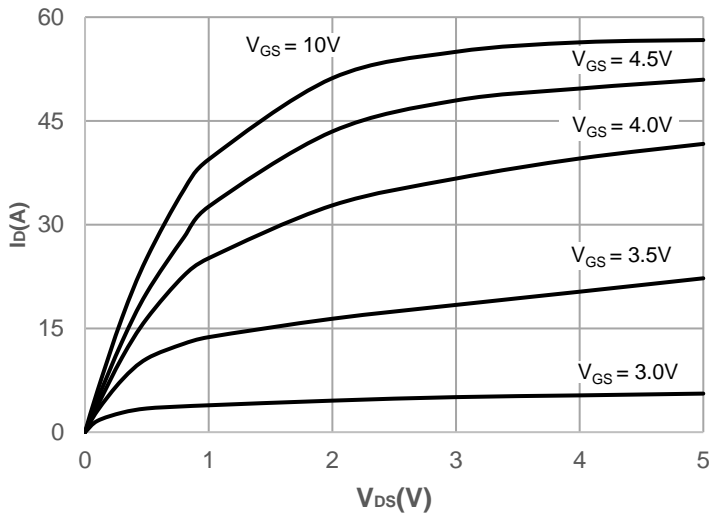


Figure 6: Typical Transfer Characteristics

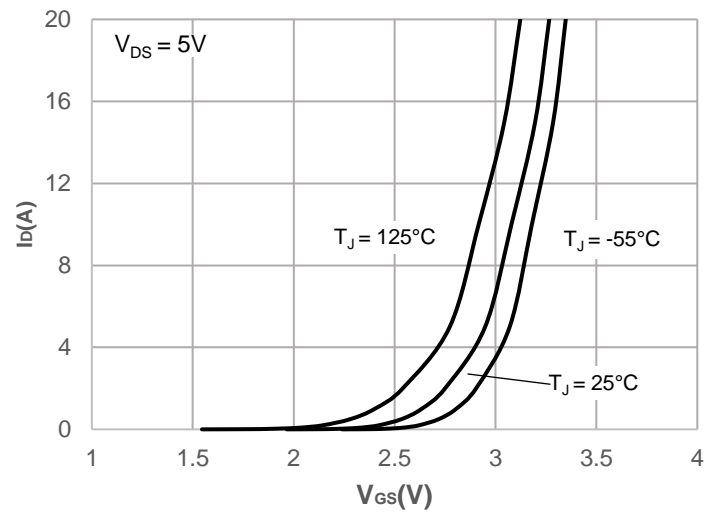


Figure 7: On-resistance vs. Drain Current

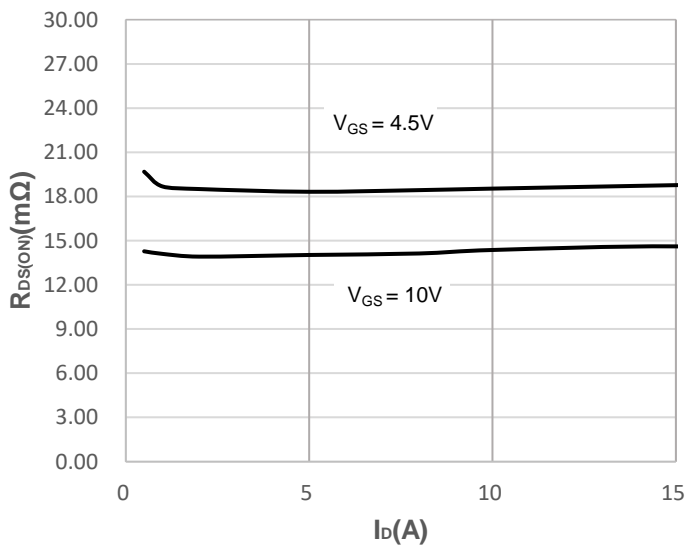


Figure 8: Body Diode Characteristics

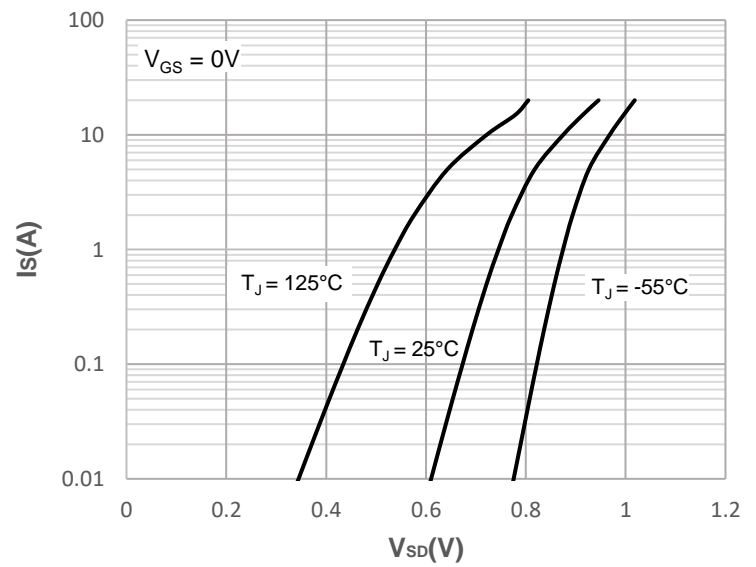


Figure 9: Gate Charge Characteristics

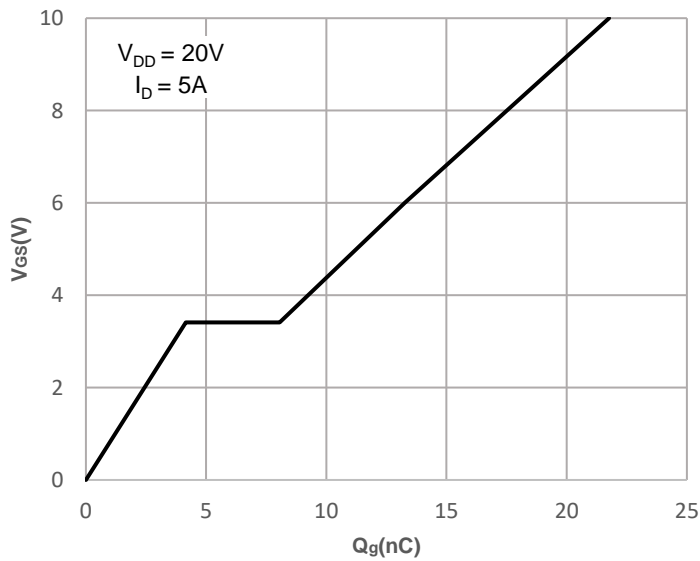
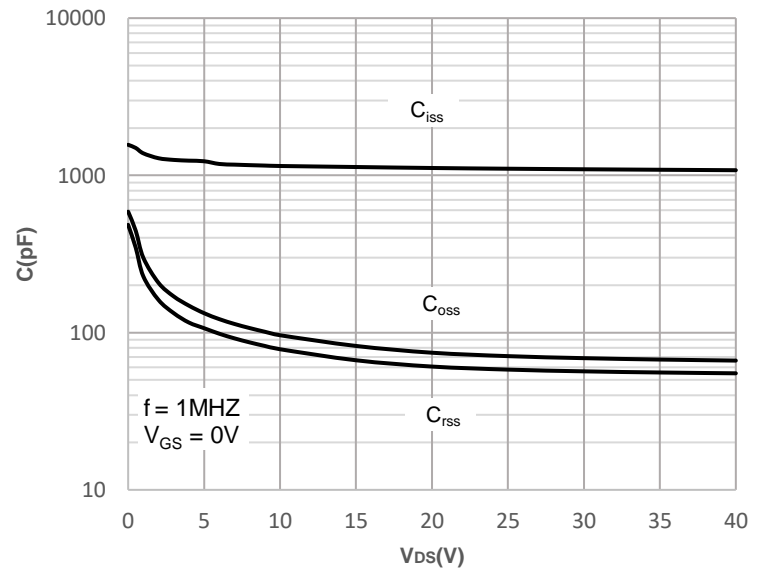


Figure 10: Capacitance Characteristics



## Typical Performance Characteristics-N

Figure 11: Normalized Breakdown voltage vs. Junction Temperature

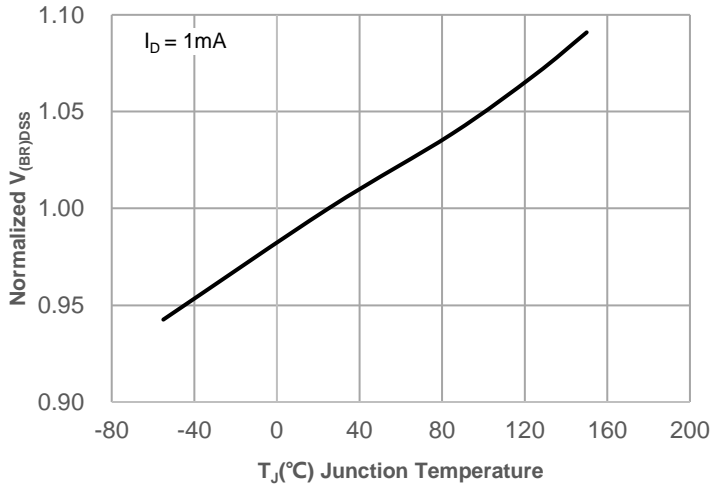


Figure 12: Normalized on Resistance vs. Junction Temperature

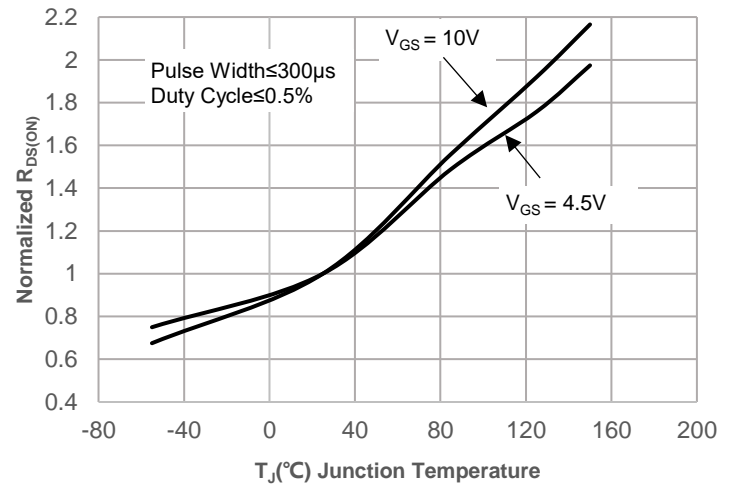


Figure 13: Normalized Threshold Voltage vs. Junction Temperature

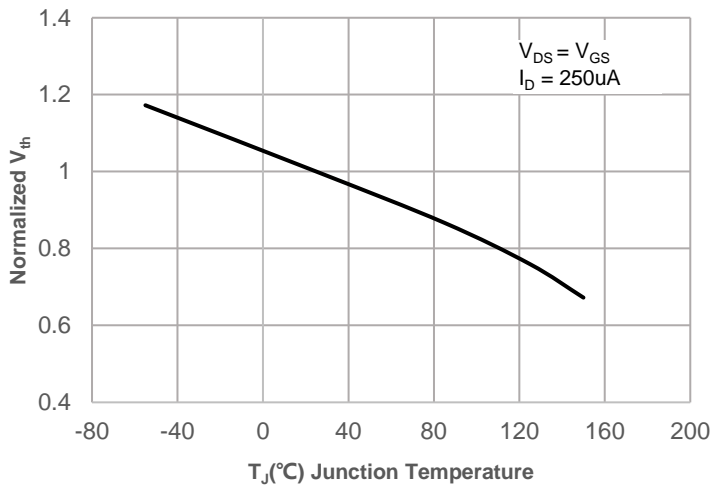


Figure 14:  $R_{DS(ON)}$  vs.  $V_{GS}$

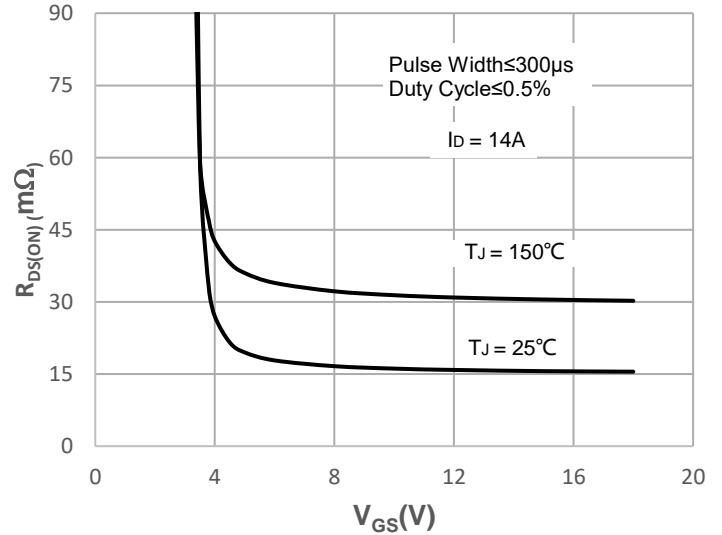
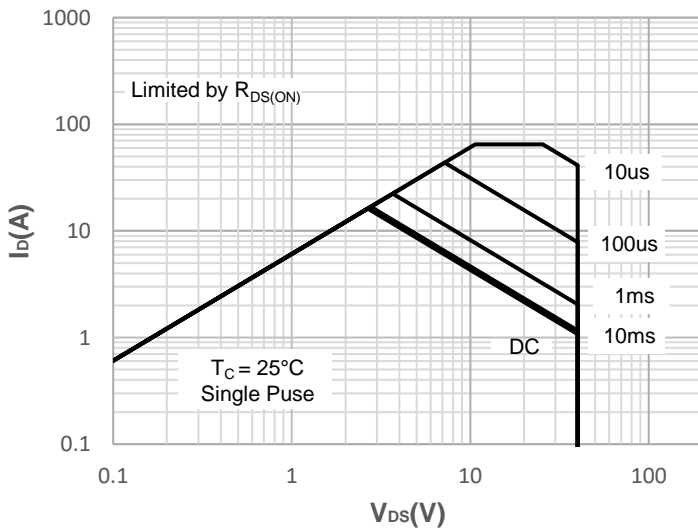


Figure 15: Maximum Safe Operating Area



## Typical Performance Characteristics-P

Figure 1: Power De-rating

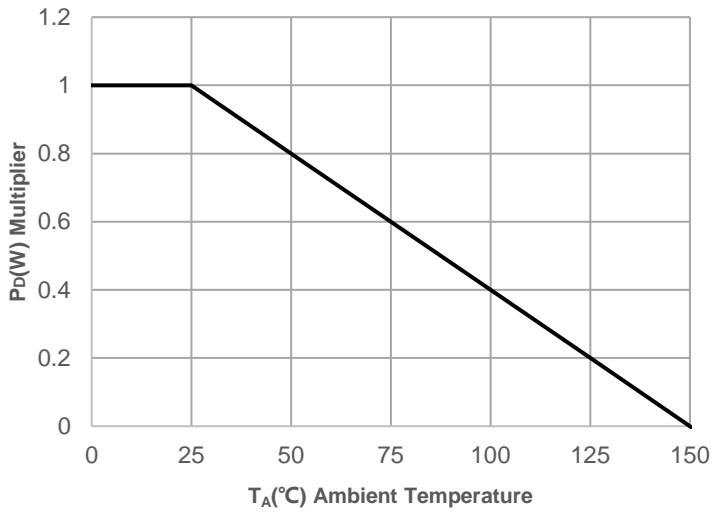


Figure 2: Current De-rating

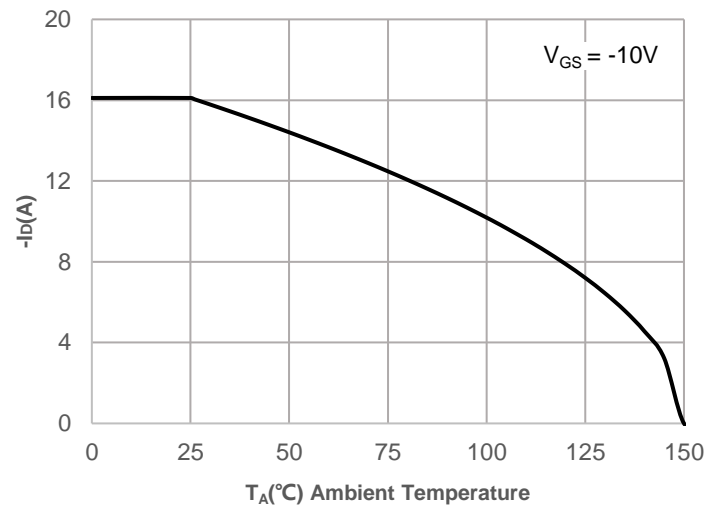


Figure 3: Normalized Maximum Transient Thermal Impedance

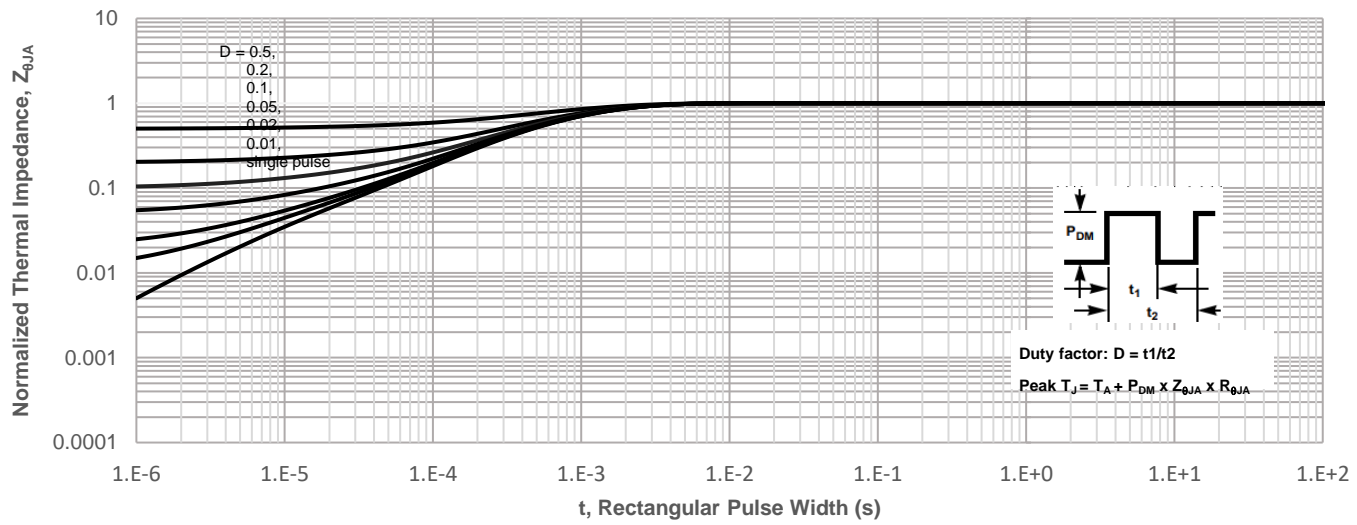
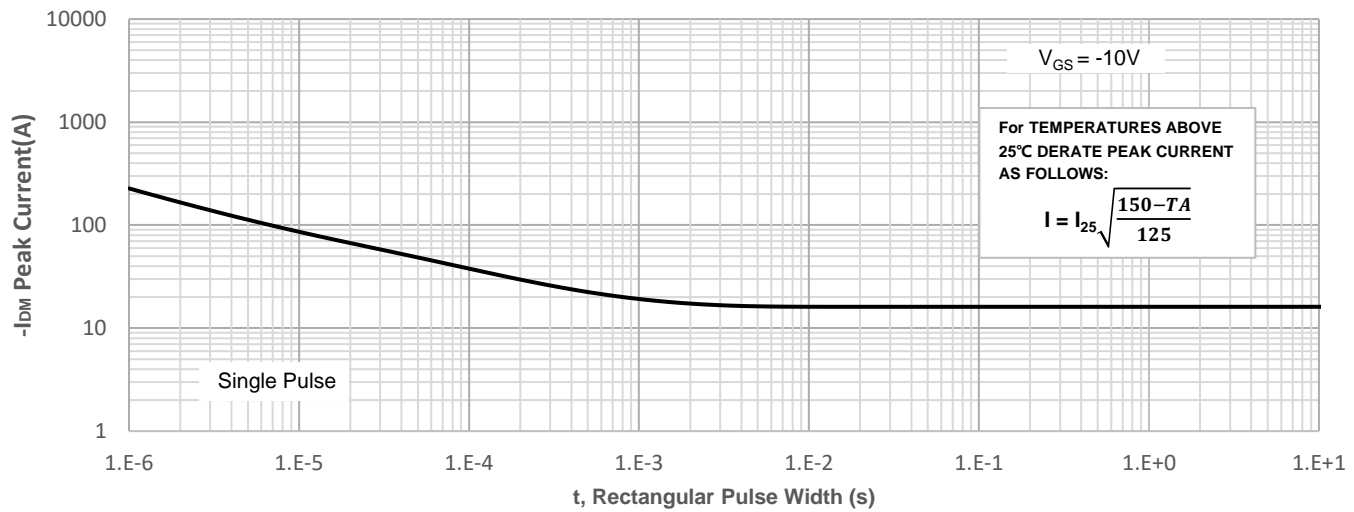
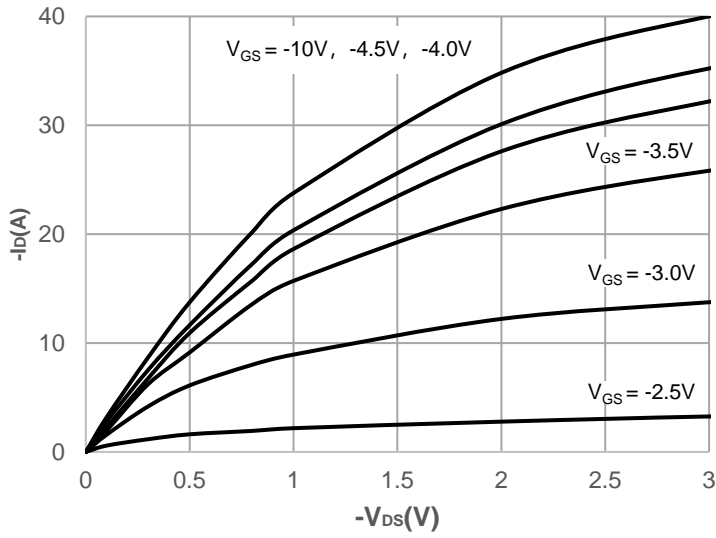
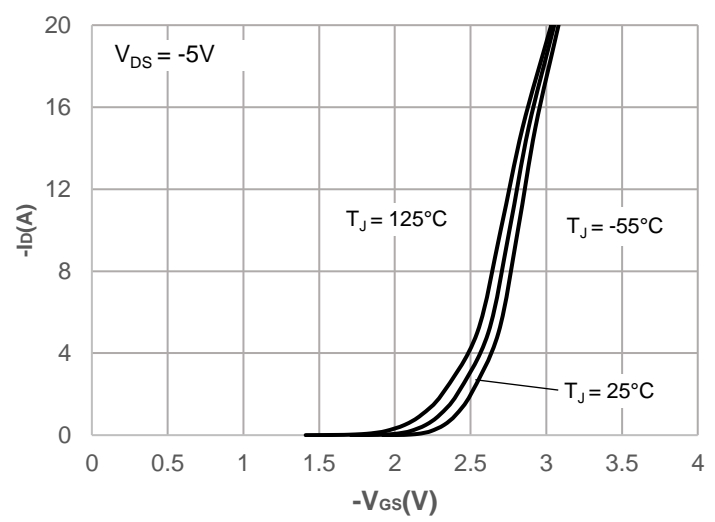
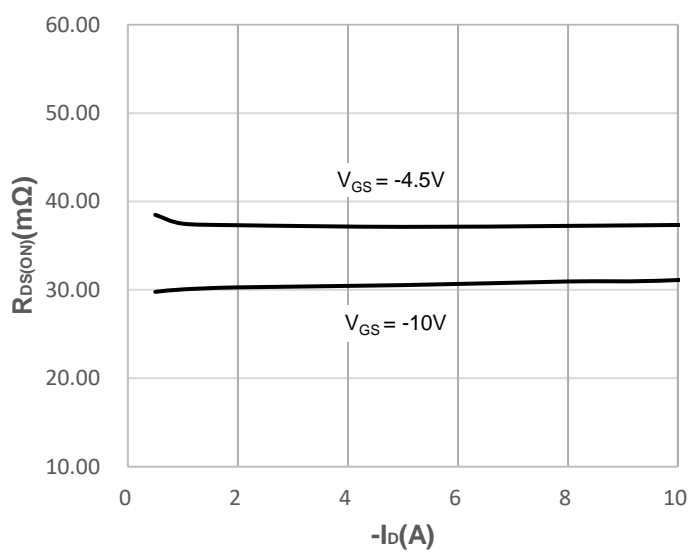
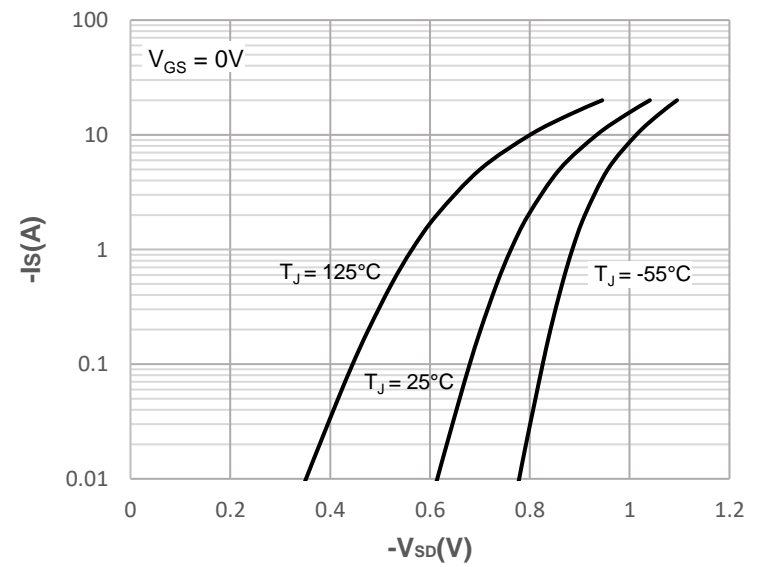
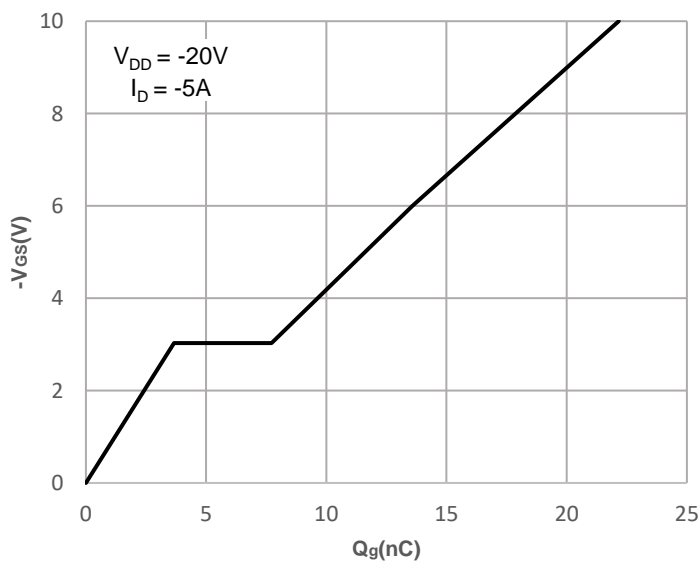
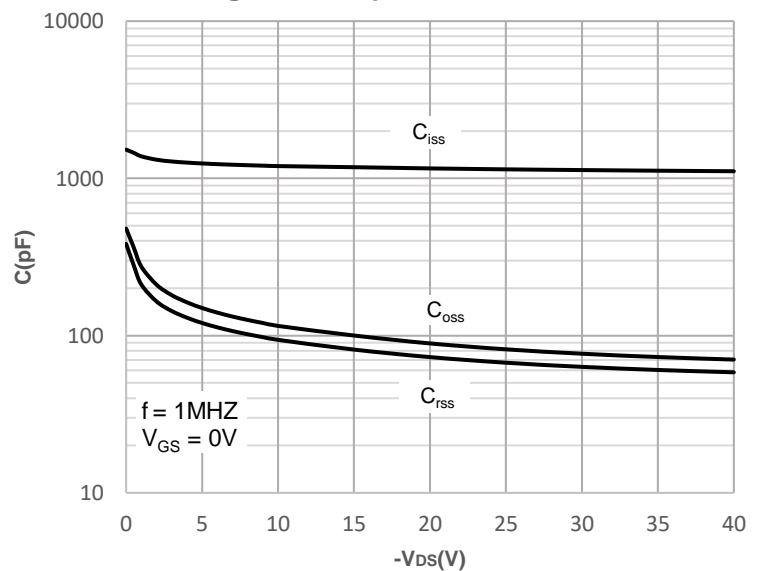


Figure 4: Peak Current Capacity



## Typical Performance Characteristics-P

**Figure 5: Output Characteristics**

**Figure 6: Typical Transfer Characteristics**

**Figure 7: On-resistance vs. Drain Current**

**Figure 8: Body Diode Characteristics**

**Figure 9: Gate Charge Characteristics**

**Figure 10: Capacitance Characteristics**




## Typical Performance Characteristics-P

Figure 11: Normalized Breakdown voltage vs. Junction Temperature

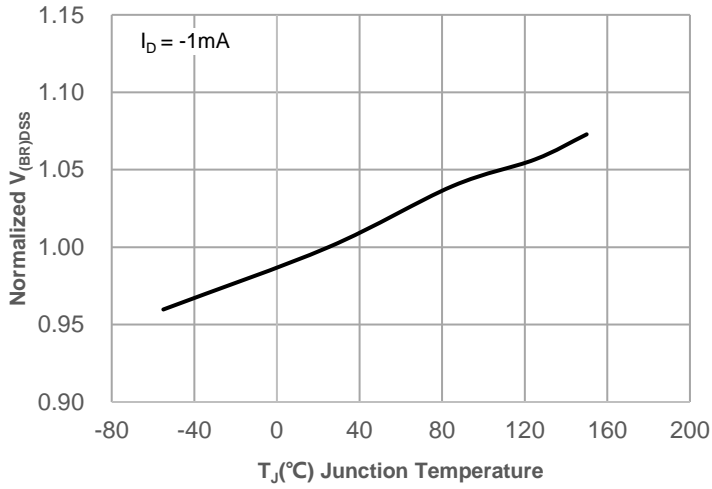


Figure 12: Normalized on Resistance vs. Junction Temperature

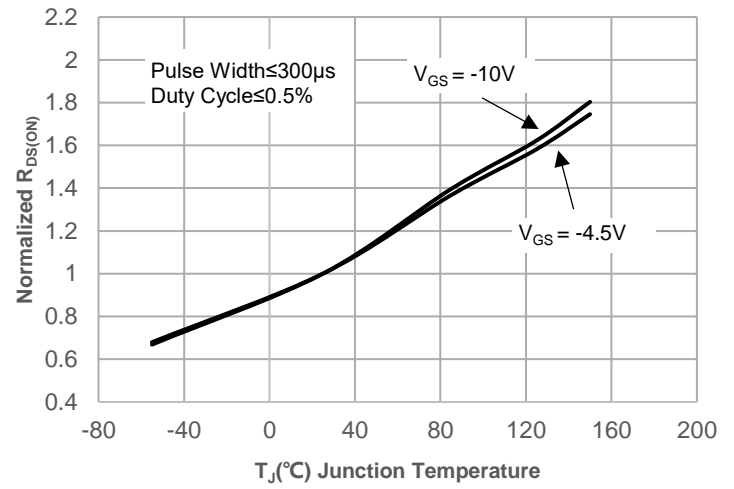


Figure 13: Normalized Threshold Voltage vs. Junction Temperature

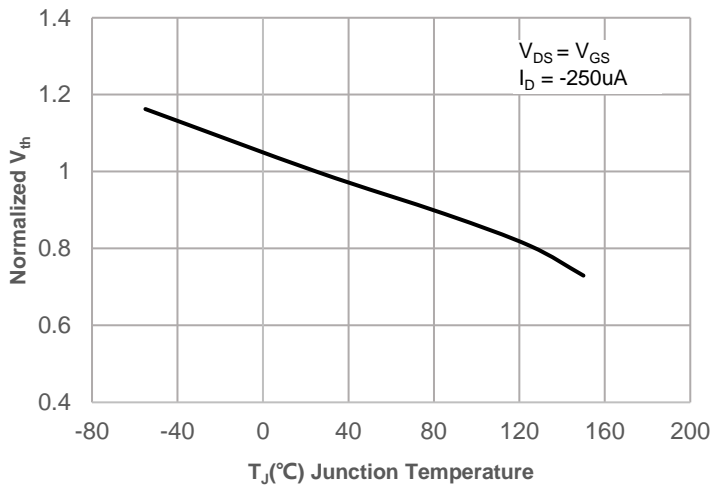


Figure 14: R\_DS(ON) vs. V\_GS

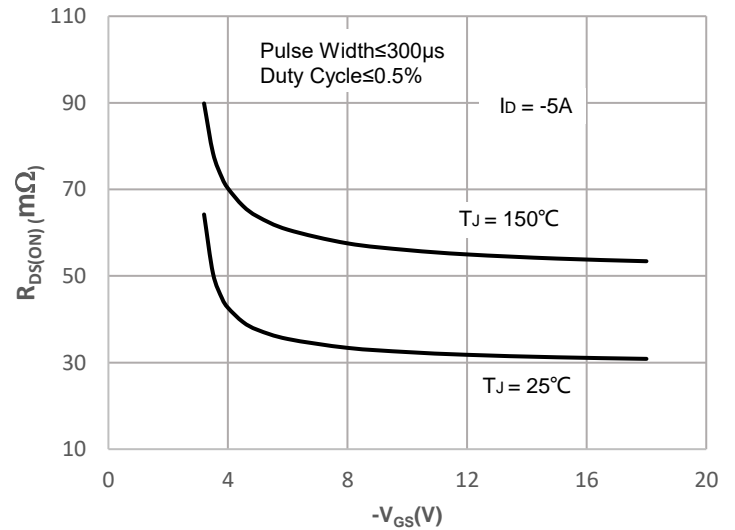
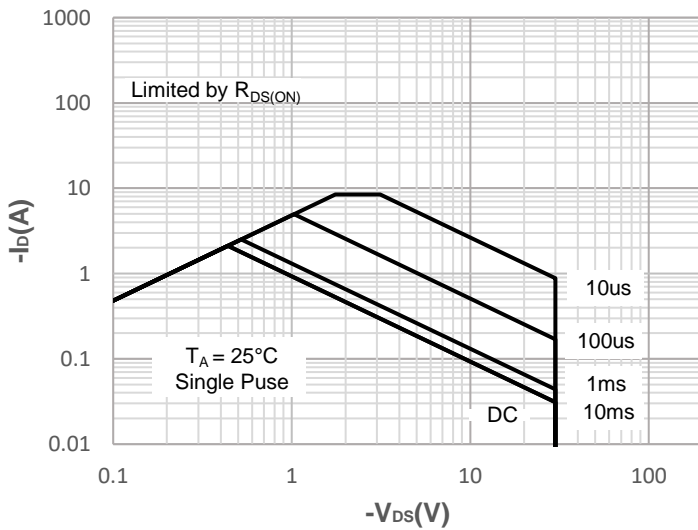


Figure 15: Maximum Safe Operating Area



### Test Circuit

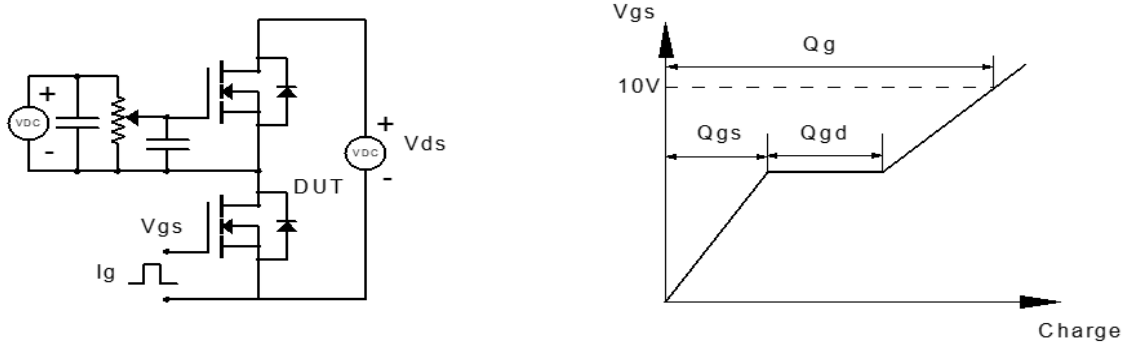


Figure 1: Gate Charge Test Circuit & Waveform

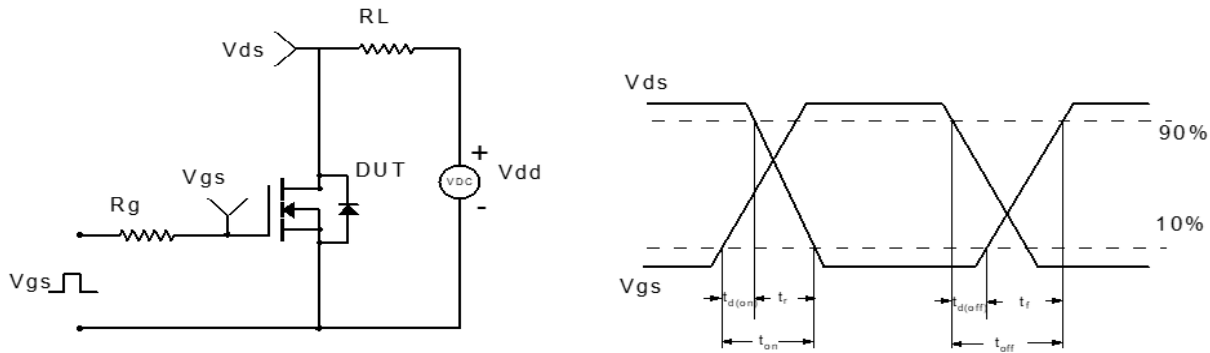


Figure 2: Resistive Switching Test Circuit & Waveform

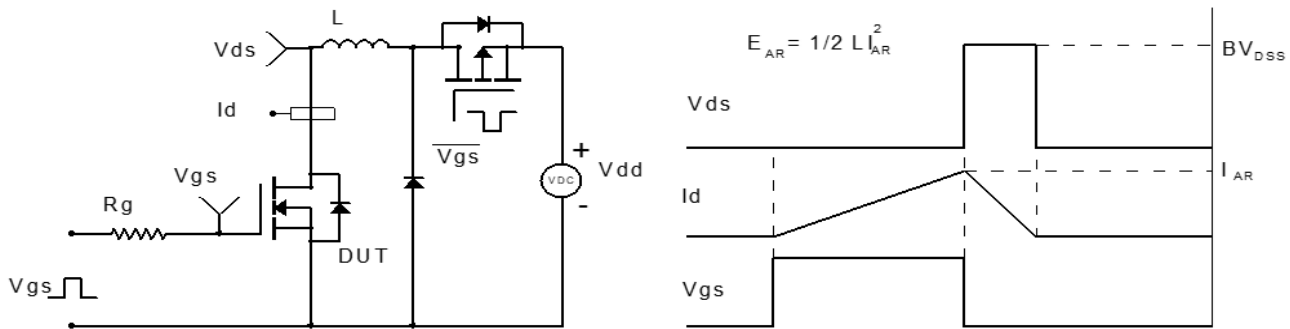


Figure 3: Unclamped Inductive Switching Test Circuit & Waveform

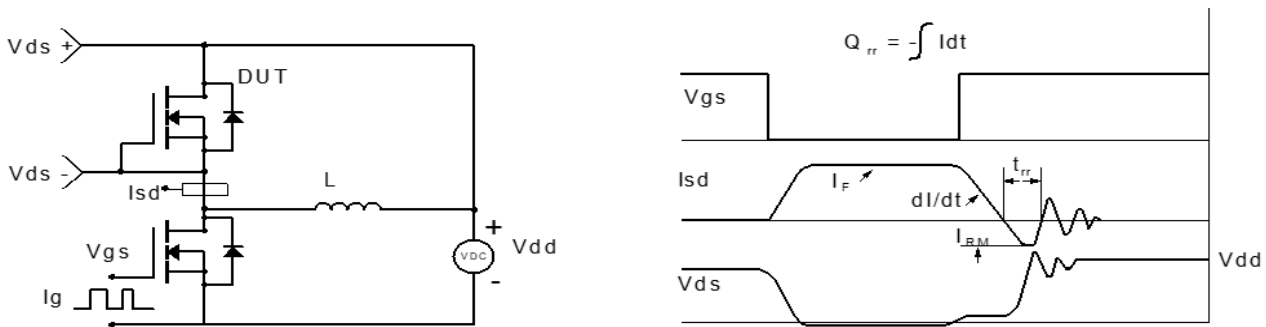


Figure 4: Diode Recovery Test Circuit & Waveform



### Test Circuit

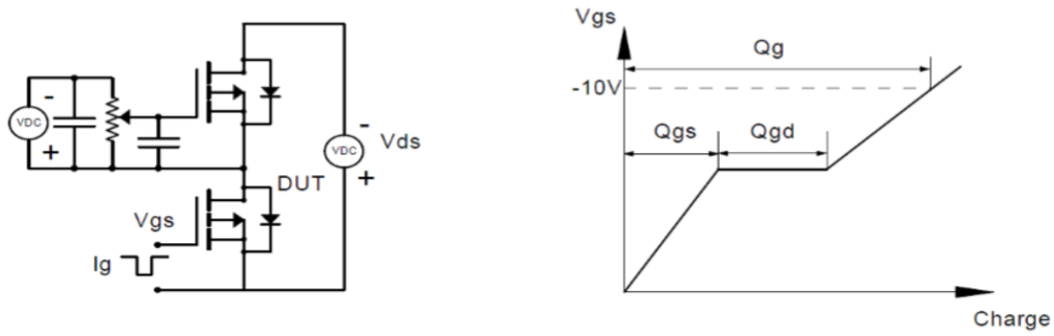


Figure 1: Gate Charge Test Circuit & Waveform

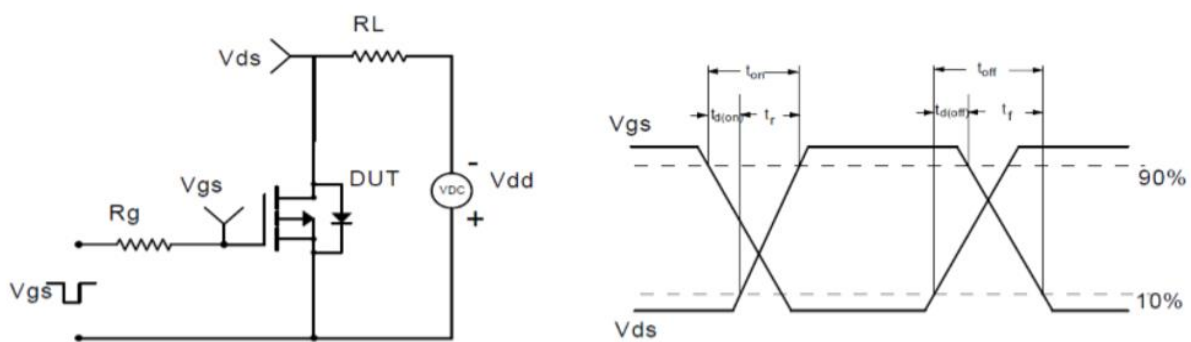


Figure 2: Resistive Switching Test Circuit & Waveform

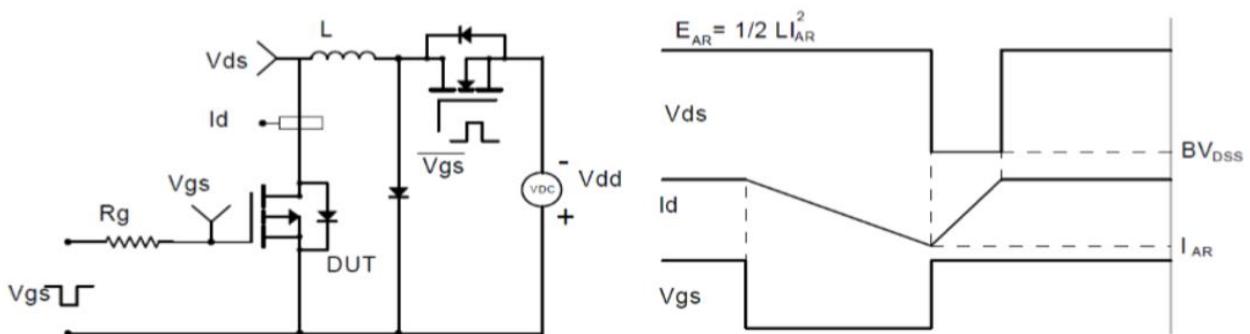


Figure 3: Unclamped Inductive Switching Test Circuit & Waveform

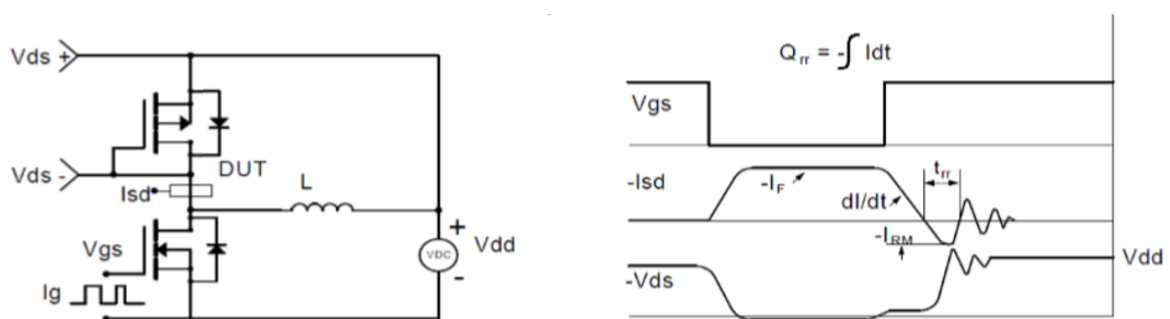
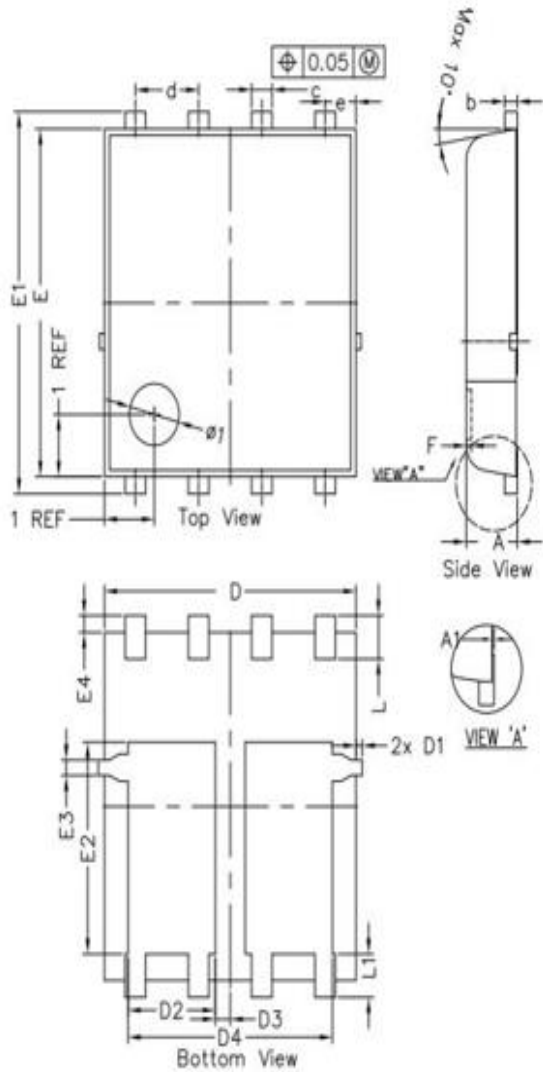


Figure 4: Diode Recovery Test Circuit & Waveform



**Package Mechanical Data(PDFN5X6-8L-D)**


SYMBOLS	DIMENSION IN MM			DIMENSION IN INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
* A	0.900	1.000	1.100	0.035	0.039	0.043
A1	0.000	---	0.050	0.000	----	0.002
b	0.246	0.254	0.312	0.010	0.010	0.012
* c	0.310	0.410	0.510	0.012	0.016	0.020
d	1.27 BSC			0.050 BSC		
* D	4.950	5.050	5.150	0.195	0.199	0.203
*D1	---	---	0.125	---	---	0.005
*D2	1.650	1.750	1.850	0.065	0.069	0.073
D3	0.200	0.300	0.400	0.008	0.012	0.016
D4	4.000	4.100	4.200	0.157	0.161	0.165
e	0.62 BSC			0.024 BSC		
* E	5.500	5.600	5.700	0.217	0.220	0.224
* E1	6.050	6.150	6.250	0.238	0.242	0.246
E2	3.310	3.410	3.510	0.130	0.134	0.138
E3	0.150	0.250	0.350	0.006	0.010	0.014
* E4	0.175	0.275	0.375	0.007	0.011	0.015
F	-	-	0.100	-	-	0.004
* L	0.500	0.600	0.700	0.02	0.02	0.03
L1	0.600	0.700	0.800	0.02	0.03	0.03

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